



# Design Specification



Rev 2

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## Document details

Title: mangOH Green User Guide

Author: Sierra Wireless

Source: <http://mangoh.io/>

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## Revision History

Revision number	Release date	Changes
1	June 2015	Creation (limited release)
2	January 2016	Added power class and height class specifications Removed PWM Added 'Class C' temperature spec to <a href="#">Table 2-1 on page 12</a> Added <a href="#">Module Power Category on page 13</a> Added <a href="#">Module Height Category on page 23</a> Updated <a href="#">Figure 4-2 on page 24</a> (pad dimension 2.10 replaces 1.60) Added <a href="#">Figure 4-4 on page 26</a> Updated <a href="#">Table 4-2 on page 27</a> (board name field size; added example header columns; added 'Additional fields') Updated <a href="#">Figure 5-3 on page 35</a> (added Detail A and Detail B) Updated <a href="#">Figure 5-4 on page 36</a> (added Detail A and Detail B) Added <a href="#">Self-enclosed IoT Module on page 37</a>

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# 1: Introduction

# 1

## 1.1 Overview

The IoT Module form factor represents an open hardware standard for sensors, network adapters, and other IoT technologies that can be "plugged" into host applications to provide new features and interfaces. As a family, IoT Modules share a standardized footprint and pinout, with several interfaces to support various IoT technologies.

## 1.2 Rationale for the IoT Module Form Factor

The IoT Module form factor is designed to be a cost-competitive solution for several current and emerging market demands for host applications, including:

- On-demand hardware applications—The same host application can be used for different market segments by including unique IoT Module solutions for each segment. For example, a Wi-Fi/Bluetooth solution for one segment and an environmental sensor for another segment.
- Electrical and feature compatibility across IoT technologies—Availability of several data interfaces allows support for various IoT solutions. For example, digital audio over PCM, application control and data transfer over USB, etc.
- Enables Configure/Built to Order
- Accommodates various PAN technologies, sensors, and other IoT applications

Using the IoT Module's modular design, all actors of the M2M value chain can benefit.

- Host applications can, without requiring redesign, inherit new features and interfaces for their products
- Technology specialists such as PAN, LPRF, Industrial Fieldbuses or sensors can bring their modules to market
- System integrators and end customers can easily combine host applications and IoT Modules to fit their specialized needs

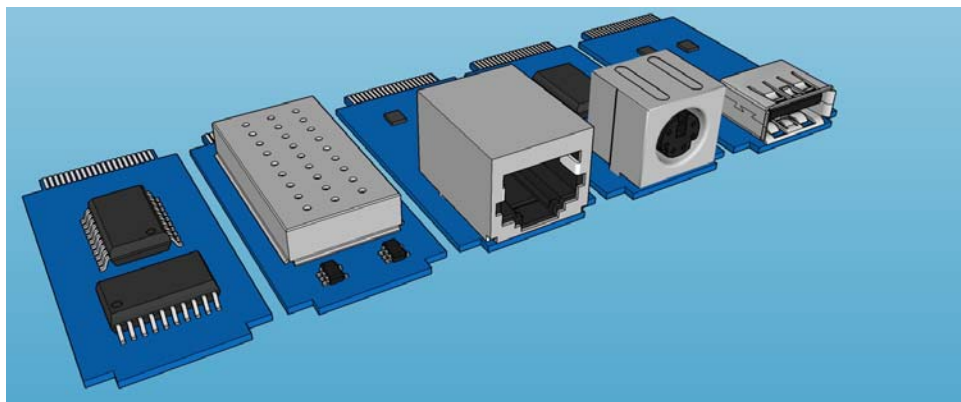


Figure 1-1: IoT Modules—Common footprint, variable designs

## 1.3 Specification Objective

This document defines a standard open-hardware pluggable module form factor specification. The specification describes supported interfaces and the mechanical design requirements (device-side and host-side) for building IoT Modules and integrating them into host applications.

## 1.4 Targeted Applications

The IoT Module form factor provides a common platform for OEMs to make a wide range of technologies available for use with IoT Module-compatible host applications. Some examples of technologies that could be implemented on IoT Modules include:

- PAN (Personal Area Network): Wi-Fi, Bluetooth, Zigbee, etc.
- Common LAN/WAN: Ethernet, USB, Serial, etc.
- Low power and Low Power Long Range wireless technologies
- Industrial Fieldbuses: Modbus, Profibus, MPI, PPI
- Global Navigation Satellite Systems (GNSS)
- Specialized I/Os: Digital, Analog, Counting, PT1000, etc.
- Sensor networks
- Specialized sensors: Accelerometers, Temperature, Environment

## 1.5 IoT Module Classes and Categories

The IoT Module specification defines module classes based on their power consumption (three categories) and module height (two categories). See [Module Power Category on page 13](#) and [Module Height Category on page 23](#) for details.

## 1.6 IoT Module Characteristics

Key characteristics of the IoT Module specification include:

- Standard footprint
- Support for wide modules (up to 8 slots wide)
- Low-cost connectors
- Several available host interfaces:
  - ADC
  - GPIOs
  - I2C
  - I<sup>2</sup>S
  - PCM
  - PPS Clock (Stratum 1)
  - SPI
  - UART
  - USB
  - SDIO

## 1.7 Document Organization

- [Technical Specifications](#)—Environmental, EMC/ESD, and power specifications
- [Interfaces Specification](#)—Host interface details for all supported interfaces
- [Mechanical / Form factor](#)—Operational specifications, and hardware design (host and IoT Module) requirements
- [Mounting methods](#)—Mounting design details (host and IoT Module)
- [Pinout](#)—Connector pin details

## 2: Technical Specifications

### 2.1 Overview

This chapter describes environmental, EMC/ESD, and power specifications for IoT Modules.

### 2.2 Environmental Specifications

IoT Modules must satisfy the operational and non-operational environmental specifications defined in Table 2-1.

**Table 2-1: Environmental Specifications**

Parameter	Range	Operating Class
Ambient Operating Temperature	-30°C to +70°C	Class A—The host application and IoT Module remain fully functional across the specified temperature range, meeting the cellular performance requirements of ETSI or other appropriate wireless standards.
	-40°C to +85°C	Class B—The host application and IoT Module remain fully functional across the specified temperature range. Some cellular parameters may deviate from the performance requirements of ETSI or other appropriate wireless standards.
	0°C to +50°C	Class C—Commodity Class. The host application and IoT Module remain fully functional across the specified temperature range, meeting the cellular performance requirements of ETSI or other appropriate wireless standards.
Ambient Storage Temperature	-40°C to +85°C	

### 2.3 Power Requirement

IoT Modules are powered by DC power provided by the host application via the pins (voltage rails) described in Table 2-2.

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*Note: Hot-swapping (hot-plugging) of IoT Modules is not supported.*

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**Table 2-2: Power Supply Pins**

Pin	Name	Function	Specification	Notes
1	VCC_5V0	USB power supply/5V power supply	5.0V $\pm$ 10%, 500 mA	
11	VCC_1V8	1.8V power supply	1.8V $\pm$ 10%, 500 mA	

Table 2-2: Power Supply Pins (Continued)

Pin	Name	Function	Specification	Notes
28	VCC_3V3	3.3V power supply	3.3V $\pm$ 10%, 500 mA	Each pin must be capable of 500 mA. IoT Modules may require up to 1 A total.
29	VCC_3V3	3.3V power supply	3.3V $\pm$ 10%, 500 mA	
Maximum combined power across all voltage rails (pins 1, 11, 28, 29)			3.3W	

### 2.3.1 Required Power-up Procedure

To prevent the possibility of latchup during the power-up sequence:

1. Host application must provide power rails (5V and 3.3V) first.
2. After power rails are provided, host application can provide I/O voltage (1.8V).

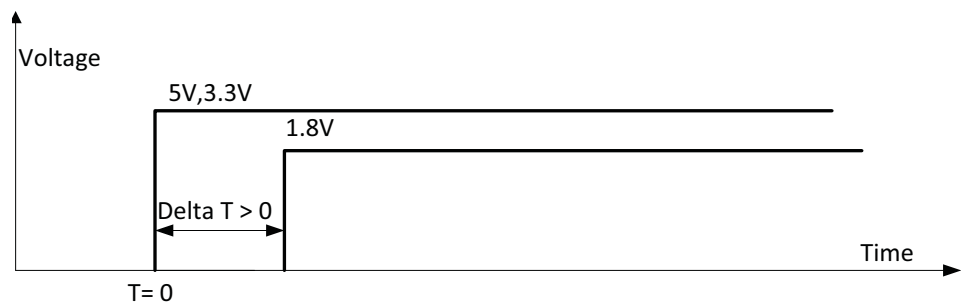


Figure 2-1: Power-up Sequence Timing

*Note: Well-designed host applications will follow this procedure to make sure latchup will not occur. IoT Module developers may also include, if desired, latchup-resistant chips and/or a latchup protection technology (LPT) circuit to prevent latchup during the power-up sequence.*

### 2.3.2 Module Power Category

IoT Modules are assigned a power category based on their power consumption:

- Category 1: <2.5W
- Category 2:  $\geq 2.5W$  to <3.3W
- Category 3:  $\geq 3.3W$

The power category is identified in the EEPROM header (see [EEPROM Header on page 27](#)).

## 2.4 EMC and ESD Recommendations

When designing an IoT Module, make sure that potential EMC (Electromagnetic Compatibility) issues are considered, and appropriate ESD protection is incorporated in the design.

For example:

- Identify and mitigate possible spurious emissions radiated by the application to the host application's RF receiver in the receiver band.
- ESD protection is strongly recommended on the IoT Module on all externally-accessible signals, such as:
  - Serial link
  - USB
  - Antenna port
  - Ethernet
- Perform EMC/ESD tests on IoT Module board as soon as possible to detect potential issues
- Follow generic EMI mitigation philosophies
  - For high-speed buses, place decoupling capacitor close to IoT Module connector in case it is needed for signal speed reduction
  - Place bulk capacitors close to power rails. Ratings for these capacitors depend on the specific IoT Module design.
- Provide ESD protection ground strips underneath the IoT Module. Host applications should include ESD protection in the form of ground clips that engage with the IoT Module's ground protection strips. For details, see [Mounting methods on page 33](#).
- If appropriate, place series resistors inline with high speed traces to drop speed and eliminate ringing effects. For example, place 33  $\Omega$  resistors inline on SDIO traces.

**Table 2-3: ESD Specifications <sup>a</sup>**

Category	Connection	Specification
Operational	Externally-accessible signals	IEC-61000-4-2 - Level (Electrostatic Discharge Immunity Test). Contact and Air limits are specific to the end product in which the IoT Module will be installed.

a. ESD protection is highly recommended at the point where the UIM contacts are exposed, and for any other signals that would be subjected to ESD by the user.

## 3: Interfaces Specification

### 3.1 Overview

This chapter describes the interfaces supported by IoT Module form-factor devices and provides specific voltage, timing, and circuit recommendations for each interface.

### 3.2 IoT Module Platform Features

The IoT Module platform provides several interfaces for device control and data transfer:

- [USB on page 15](#)
- [SDIO Interface on page 16](#)
- [UART on page 16](#)
- [SPI Bus on page 17](#)
- [Reset Signal \(n\\_RESET\) on page 18](#)
- [ADC on page 18](#)
- [I2C Interface on page 18](#)
- [General Purpose Input/Output \(GPIO\) on page 19](#)
- [n\\_CARD\\_DETECT on page 19](#)
- [Digital Audio on page 21](#)
- [Stratum Clock \(PPS\) on page 21](#)

### 3.3 USB

The IoT Module supports one high-speed USB2.0 Interface that conforms to *[3] Universal Serial Bus Specification, Revision 2.0*. The interface may be used for application control and data transfer between the IoT Module and a host application.

**Table 3-1: USB2.0 Interface Pins**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
1	VCC_5V0	I	USB power supply/5V power supply	No connect	5.0V
2	USB_D+	I/O	Differential data interface positive	No connect	
3	USB_D-	I/O	Differential data interface negative	No connect	
4	GND	-	Ground	No connect	

a. Direction with respect to IoT Module

## 3.4 SDIO Interface

The IoT Module supports an SDIO (Secure Digital Input/Output) interface that conforms to *[4] SD Specifications Part E1 SDIO Simplified Specification, Version 3.00*. The interface may be used for data communication between the IoT Module and a host application.

The IoT Module can incorporate an SDIO card or an embedded SDIO device, as identified in the EEPROM header (see [EEPROM Header on page 27](#)). The host application must identify the SDIO type and take appropriate steps to work with it (as described in the SDIO specification).

**Table 3-2: SDIO Interface Pins**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
5	SDIO_CLK	I	SDIO clock	No connect	SDIO card: 2.7–3.6V
6	SDIO_CMD	I	Command/Response	No connect	
7	SDIO_DAT3/CD	I/O	Data 3/Card Detection	No connect	Embedded SDIO device: 1.7–1.95V or 2.7–3.6V
8	SDIO_DAT2	I/O	Data 2	No connect	
9	SDIO_DAT1	I/O	Data 1	No connect	See ([4] SD Specifications Part E1 SDIO Simplified Specification, Version 3.00 for details.
10	SDIO_DAT0	I/O	Data 0	No connect	

a. Direction with respect to IoT Module

## 3.5 UART

The IoT Module supports a 4-wire UART interface. The interface may be used for data communication between the IoT Module and a host application.

Flow control is managed using the RTS/CTS signals, or using software XON/XOFF.

For additional information, see [Digital I/O Characteristics on page 22](#).

**Table 3-3: UART Interface Pins**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
12	UART_TXD	O	UART Transmit Data	No connect	1.8V ± 10%
13	UART_RXD	I	UART Receive Data	No connect	
14	UART_CTS	I	UART Clear to Send	No connect	
15	UART_RTS	O	UART Ready to Send	No connect	

a. Direction with respect to IoT Module



## 3.6 SPI Bus

The IoT Module supports a 3/4/5-wire serial peripheral interface (SPI) that may be used for data communication between the IoT Module and a host application.

The following features are available on the SPI bus:

- Mode: Slave (Master mode is not supported)
- 3/4/5-wire interface

*Note: Although the IoT Module supports 3, 4, and 5-wire implementations of the SPI bus, the module will only work if the host application supports the same architecture (number of signals, bus speed, data length) as the module.*

**Table 3-4: SPI Interface Pins**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
16	SPI_CLK	I	SPI serial clock	No connect	1.8V $\pm$ 10%
17	SPI_MISO	O	SPI2 Master Input/ Slave Output (Data transfer from IoT Module to host application)	No connect	
18	SPI_MOSI	I	SPI Master Output/ Slave Input (Data transfer from host application to IoT Module)	No connect	
19	SPI_SS/MRDY	I	SPI Slave Select	No connect	
26	SPI_SRDY (alternate function)	O	SPI Slave Ready	No connect	

a. Direction with respect to IoT Module

### 3.6.1 SPI Configuration

**Table 3-5: SPI Configuration**

Operation	Max Speed	SPI-Mode	Duplex	4-wire Type
Slave	Host application-dependent	0,1,2,3	Full	SCLK (SPI_CLK) MOSI (SPI_MOSI) MISO (SPI_MISO) SS (SPI1_SS/MRDY)

## 3.7 Reset Signal (n\_RESET)

The IoT Module supports an interface that allows an external application to reset the device.

When the host application brings up the power rails for the IoT Module, n\_RESET is pulled high.

To reset the IoT Module, the host must pulse n\_RESET low.

**Table 3-6: n\_RESET Interface Pin**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
32	n_RESET	I	Active low reset from host application to IoT Module	No connect	1.8V ± 10%

a. Direction with respect to IoT Module

## 3.8 ADC

The IoT Module supports one general purpose Analog to Digital Converter (ADC) output.

The interface may be used for one-way (output) communication from the IoT Module to the host application. For example, ADC0 could be used as an indicator to the host application to notify when a specific analog event occurs (such as a sensor being triggered).

**Table 3-7: ADC0 Interface Pin**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
20	ADC0	O	Analog to Digital Converter	No connect	1.8V ± 10%

a. Direction with respect to IoT Module

## 3.9 I<sup>2</sup>C Interface

The IoT Module supports one I<sup>2</sup>C (Inter-Integrated Circuit) interface. The interface may be used for data communication between the IoT Module and a host application.

The I<sup>2</sup>C bus implemented on the IoT Module should support 100 kbps (standard mode) to be compatible with the widest variety of host applications. Higher speeds may also be implemented (for example, 400 kbps, 1 Mbps, etc.) but will only be attainable if also supported by the host application.

The I<sup>2</sup>C interface has the following hardware requirements:

- Host application—All required pull-up resistors, including a weak pull-up for the I<sup>2</sup>C bus, should be located on the host application, not on the IoT Module. Resistor values are host-dependent. For pull-up details, see [Pull-up Resistors on page 32](#).

- IoT Module—A configuration EEPROM is required. For details, see [n\\_CARD\\_DETECT on page 19](#) and [EEPROM on page 26](#).

**Table 3-8: I<sup>2</sup>C Interface Pins**

Pin	Signal name	I/O <sup>a</sup>	Function	If unused	Voltage
22	I2C_SDA	I/O	I <sup>2</sup> C Data (Tx/Rx)	No connect	1.8V ± 10%
23	I2C_SCL	I	I <sup>2</sup> C Clock	No connect	1.8V ± 10%

a. Direction with respect to IoT Module

## 3.10 General Purpose Input/Output (GPIO)

The IoT Module supports four GPIOs that may be used for data communication between the IoT Module and a host application.

For additional information, see [Digital I/O Characteristics on page 22](#).

**Table 3-9: GPIO Pins**

Pin	Signal name <sup>a</sup>	I/O <sup>b</sup>	Function	If unused	Voltage
24	GPIO_1 <sup>c</sup>	I/O	General purpose I/O	No connect	1.8V ± 10%
25	GPIO_2	I/O		No connect	1.8V ± 10%
26	GPIO_3	I/O		No connect	1.8V ± 10%
27	GPIO_4	I/O		No connect	1.8V ± 10%

a. Alternate functions available: pin 26: SPI\_SRDY

b. Direction with respect to IoT Module

c. May be used as an interrupt line if the module has an IRQ line

*Note: GPIOs are logic I/O signals that should not be used to directly drive electric loads.*

## 3.11 n\_CARD\_DETECT

The IoT Module provides a signal that is used by the host to detect when the IoT Module is inserted or removed from a slot on the host application.

**Table 3-10: n\_CARD\_DETECT Pin**

Pin	Signal name	I/O	Function	Voltage
31	n_CARD_DETECT	I/O	Host monitors the signal for a state change that indicates the module is inserted (active low), or removed (high)	1.8V ± 10%

[Figure 4-6 on page 30](#) describes the process the host application uses to detect when IoT Modules are inserted or removed from slots on the host application.

All IoT Modules are assigned the same address (0x53) while they are inactive. When the host needs to work with a specific module, it accesses the appropriate slot and activates the module. When finished with a module, it is deactivated, and the host can then access another module if desired.

IoT Modules can be inserted before the host application boots, or while the host application is running. The host application monitors the slots on the application board waiting for state changes on the n\_CARD\_DETECT pins, which indicate that a module has been inserted or removed.

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*Note: IoT Modules that occupy more than one slot must use the n\_CARD\_DETECT pin in the first slot.*

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*Note: n\_CARD\_DETECT must have a pull-up ( $\geq 47k$ ) on the host. For details, see [Recommended EEPROM Schematic on page 29](#) and [Pull-up Resistors on page 32](#).*

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**Table 3-11: n\_CARD\_DETECT States**

State <sup>a</sup>	Logic state	Address pin A0 (level)	EEPROM address	Comments
Input	High	High	0x53	No IoT Module detected
Input	Low	High	0x53	IoT Module is inactive
Output	High	Low	0x52	IoT Module is active

a. Direction with respect to IoT Module

## 3.12 Digital Audio

The IoT Module supports a 4-wire digital audio interface that can be configured for either PCM (Pulse Code Modulation) or I<sup>2</sup>S (Inter-IC Sound) audio.

**Table 3-12: PCM/I<sup>2</sup>S interface signals <sup>a</sup>**

Pin	Signal name	I/O <sup>b</sup>	Function	If Unused
33	PCM_DIN	Output	PCM Data In The frame “data in” relies on the selected configuration mode.	Leave open
	I2S_IN		I2S Data In The frame “data in” relies on the selected configuration mode.	
34	PCM_DOUT	Input	PCM Data Out The frame “data out” relies on the selected configuration mode.	Leave open
	I2S_OUT		I2S Data Out The frame “data out” relies on the selected configuration mode.	
35	PCM_SYNC	Input	PCM Sync The frame synchronization signal delivers an 8 kHz frequency pulse that synchronizes the frame data in and the frame data out.	Leave open
	I2S_WS		I2S Word Select The word select clock indicates which channel is currently being transmitted (low cycle indicates left audio channel, high cycle indicates right audio channel).	
36	PCM_CLK	Input	PCM Clock The frame bit clock signal controls data transfer with the audio peripheral.	Leave open
	I2S_CLK		I2S Clock The frame bit clock signal controls data transfer with the audio peripheral.	

a. All values are preliminary and subject to change.

b. Direction with respect to IoT Module

## 3.13 Stratum Clock (PPS)

The IoT Module accepts a Stratum 1 clock input (PPS signal) from the host application. The host application should operate as a stratum 1 time source, connected to GPS (a stratum 0 source).

This signal can then be used to manage timing for sensor nodes (or other devices) that are attached to the IoT module.

For additional information, see [Digital I/O Characteristics on page 22](#).

**Table 3-13: Clock interface pin descriptions**

Pin	Signal name	I/O	I/O type	Description	If Unused
37	PPS	Input	1.8V	Stratum Clock 1 Pulse per second signal.	No connect

## 3.14 Digital I/O Characteristics

The I/O characteristics for supported 1.8V digital interfaces (GPIOs, UART, PPS) are described in the following table.

**Table 3-14: Digital I/O Characteristics ( $V_{DD\_PX} = 1.80\text{ V (nominal)}$ )<sup>a</sup>**

Parameter		Comments	Min	Typ	Max	Units
V <sub>IH</sub>	High level input voltage	CMOS/Schmitt	0.65 * V <sub>DD_PX</sub>	-	V <sub>DD_PX</sub> + 0.3	V
V <sub>IL</sub>	Low level input voltage	CMOS/Schmitt	-0.3	-	0.35 * V <sub>DD_PX</sub>	V
V <sub>SHYS</sub>	Schmitt hysteresis voltage		100	-	-	mV
I <sub>IH</sub>	Input high leakage current <sup>b</sup>	No pull-down	-		1	μA
I <sub>IL</sub>	Input low leakage current <sup>c</sup>	No pull-up	-1		-	μA
R <sub>P</sub>	Pull up/down resistance		55		390	kΩ
V <sub>OH</sub>	High level output voltage	CMOS, at pin-rated drive strength	V <sub>DD_PX</sub> - 0.45	-	V <sub>DD_PX</sub>	V
V <sub>OL</sub>	Low level output voltage	CMOS, at pin-rated drive strength	0	-	0.45	V
I <sub>OZH</sub>	Tri-state leakage current <sup>b</sup>	Logic high output, no pull-down	-		1	μA
I <sub>OZL</sub>	Tri-state leakage current <sup>c</sup>	Logic low output, no pull-up	-1		-	μA
R <sub>K</sub>	Keeper resistance		30		150	kΩ
I <sub>ISL</sub>	Sleep crystal input leakage		-0.15	-	0.15	μA
I <sub>IHVKP</sub>	High-V tolerant input leakage	With keeper	-1	-	-	μA
C <sub>IN</sub>	Input capacitance <sup>d</sup>		-	-	5	pF
I <sub>PIN</sub>	Current per pin		-	-	16	mA

a. All values are preliminary and subject to change.

b. Pin voltage =  $V_{DD\_PX}$  max. For keeper pins, pin voltage =  $V_{DD\_PX}$  max - 0.45 V.

c. Pin voltage = GND and supply =  $V_{DD\_PX}$  max. For keeper pins, pin voltage = 0.45 V and supply =  $V_{DD\_PX}$  max.

d. Input capacitance is guaranteed by design, but is not 100% tested.

## 4: Mechanical / Form factor

### 4.1 Overview

This chapter describes mechanical specifications for the IoT Module and host devices.

### 4.2 Mechanical Dimensions

#### 4.2.1 Module Height Category

IoT Modules are assigned a height category based on the top height (distance from the top face of the PCB to the top of the tallest component on the PCB):

- Category 1:  $\leq 14.00$  mm
- Category 2:  $> 14.00$  mm

#### 4.2.2 Required Top/Bottom Clearance

[Figure 4-1](#) illustrates the space requirements between the IoT Module and a host application.

Thus, maximum component heights on the module's top and bottom face are:

- Top:
  - Category 1:  $\leq 14.00$  mm
  - Category 2:  $> 14.00$  mm
- Bottom—2.5 mm (0.5 mm clearance required to host PCB)

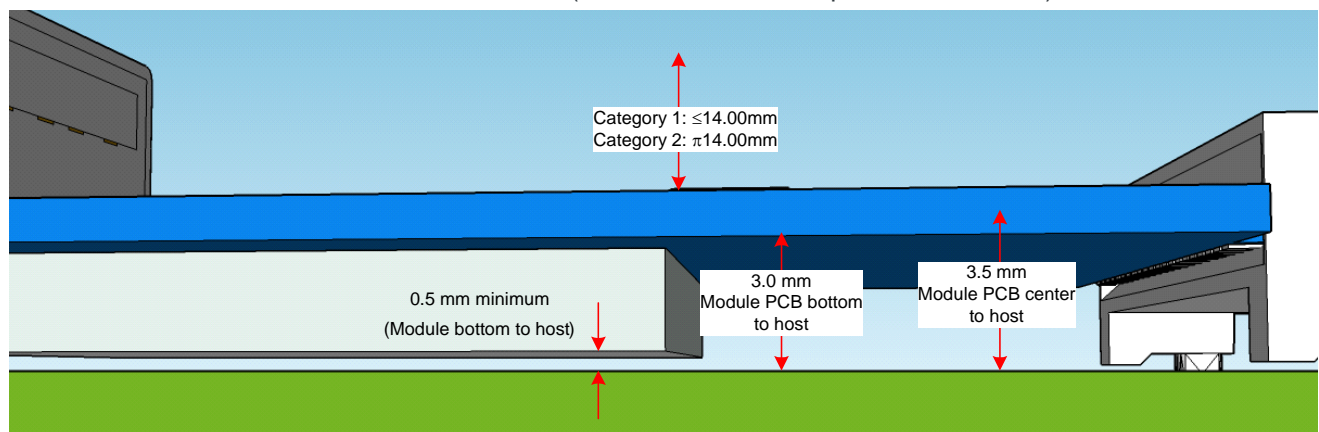


Figure 4-1: IoT Module Height Limits

IoT Modules may be designed to fit in 1–8 slots, depending on OEM design requirements. [Figure 4-2 on page 24](#) and [Figure 4-3 on page 25](#) describe the measurements for single-slot and double-slot IoT Modules respectively.

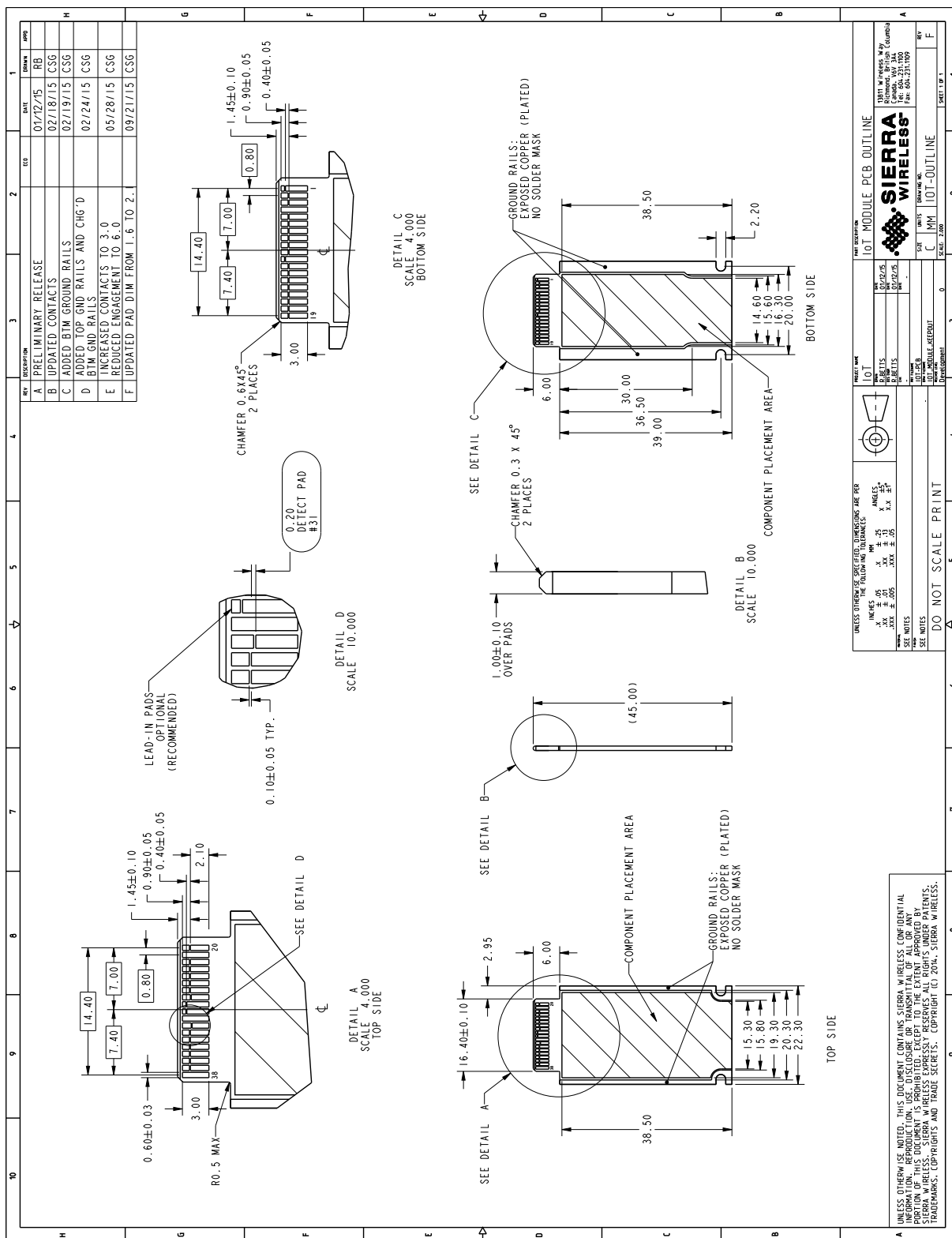
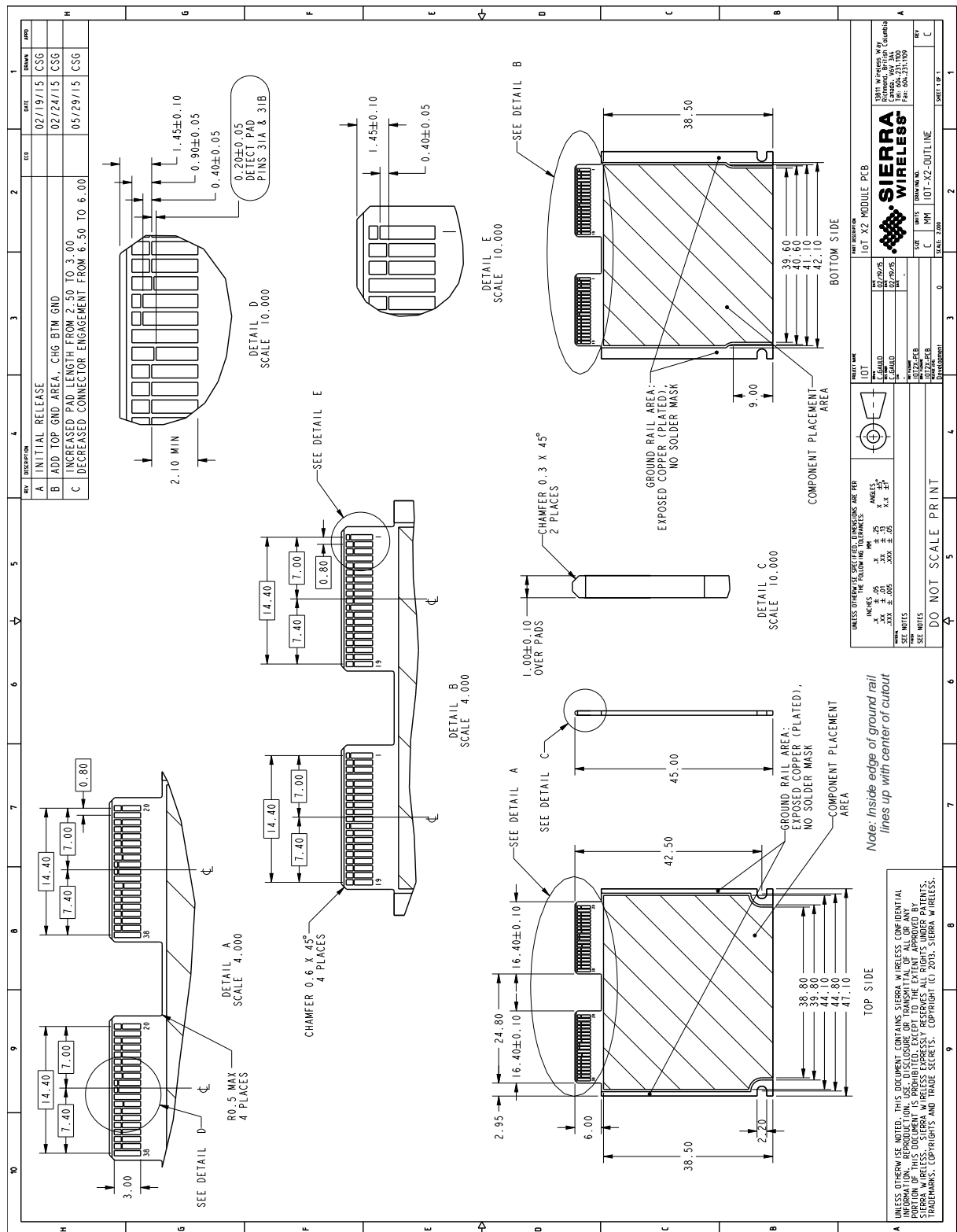


Figure 4-2: Single Slot Module Connector Details





# 4.3 Module-side Requirements and Considerations

## 4.3.1 EEPROM

Each IoT Module must use an I2C EEPROM that meets the following specifications:

Table 4-1: EEPROM Requirements

Attribute	Requirement	Options/Restrictions
Model	24Cxx type 1.8V I2C EEPROM	Other model types are not supported (for example, 3.3V or 5V)
Addressing	16-bit only	<ul style="list-style-type: none"><li>8-bit and 24-bit addressing are not supported</li><li>Address when device is inactive: 0x52</li><li>Address when device is being scanned: 0x53</li></ul>
I2C mode support	100 kHz	OEM may also support higher speeds, which will only be usable if the host application also supports the higher speeds.
Memory paging	Not supported	Do not use paged type EEPROMs.
I2C clock stretching	Not supported	Do not use EEPROMs that perform I2C clock stretching
Write protect pin	Must be supported, and must protect the entire device memory	

EEPROMs that satisfy these requirements are available from several vendors. One example is ON Semiconductor part # CAT24C32.

*Note: For double (or wider) modules, the EEPROM is read via the first slot on the card.*

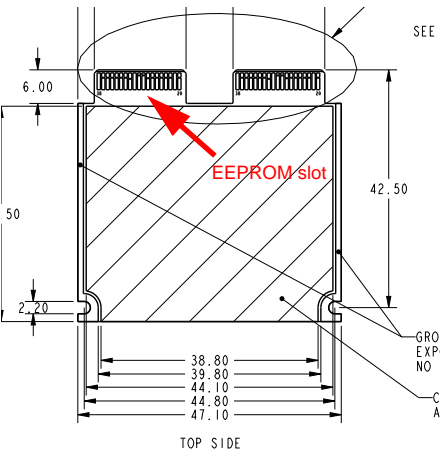


Figure 4-4: Slot location for EEPROM on wide IoT Modules

## 4.3.2 EEPROM Header

All IoT Modules must contain the following information in their EEPROMs.

*Note: EEPROM data is stored in little-endian format.*

**Table 4-2: EEPROM Structure<sup>a</sup>**

Field	Offset	Size (bytes)	Description	Example Header	
				Value	Description
Header	0	2	0xAA, 0x55	0xAA, 0x55	Signature
Header Version	2	2	0x0001	0x0001	Version 1
Board Name	4	32	<ul style="list-style-type: none"> <li>OEM-defined board description</li> <li>Null-terminated ASCII string—maximum 31 printable characters</li> </ul>	"Laser module" + '\0'	Null-terminated module name
Serial Number	36	10	IoT module serial number  Format: YYMMDDnnnn <ul style="list-style-type: none"> <li>YY = 2 digit year of production</li> <li>MM = 2 digit month of production</li> <li>DD = 2 digit day of production</li> <li>nnnn = incrementing board number</li> </ul>	"1504240001"	Year = 2015 Month = April Day = 24 Board number = 0001
Number of slots	46	1	Board width <ul style="list-style-type: none"> <li>1–8</li> <li>Note: 0 is reserved</li> </ul>	2	Double-width module
Interfaces					
Slots used for I2C	47	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000010	I2C used on slot 2
Slots used for SPI	48	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000011	SPI used on slots 1 and 2
Slots used for UART	49	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000001	UART used on slot 1
Slots used for GPIO	50	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000011	GPIO used on slots 1 and 2

**Table 4-2: EEPROM Structure<sup>a</sup> (Continued)**

Field	Offset	Size (bytes)	Description	Example Header	
				Value	Description
Slots used for SDIO	51	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000000	SDIO not used
Slots used for PCM	52	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000000	PCM not used
Slots used for ADC	53	1	<ul style="list-style-type: none"> <li>0xNN bit mask of slots on which this interface is used</li> <li>BitX = 0: Interface not used on slot X</li> <li>BitX = 1: Interface used on slot X</li> </ul>	0b00000011	Analog input used on slots 1 and 2
Additional fields					
Environmental Class	54	1	<ul style="list-style-type: none"> <li>Class letter in ASCII format</li> <li>"A", "B", "C"</li> </ul>	"A"	Class A temperature range
Power Category	55	1	<ul style="list-style-type: none"> <li>Power Class number (1 or 2)</li> </ul>	2	Power Class 2
Module Height Category	56	1	<ul style="list-style-type: none"> <li>Height Class number (1 or 2)</li> </ul>	2	Module Height Class 2
Application ID	57	64	<ul style="list-style-type: none"> <li>Null-terminated ASCII string</li> </ul>	"Sierra Wireless Home App A" + '\0'	Null-terminated application name
Trusted ID	121	64	<ul style="list-style-type: none"> <li>Null-terminated ASCII string</li> </ul>	"AzDffDHJFf12k" + '\0'	Null-terminated ID

a. Structure details are preliminary and subject to change.

### 4.3.2.1 Recommended EEPROM Schematic

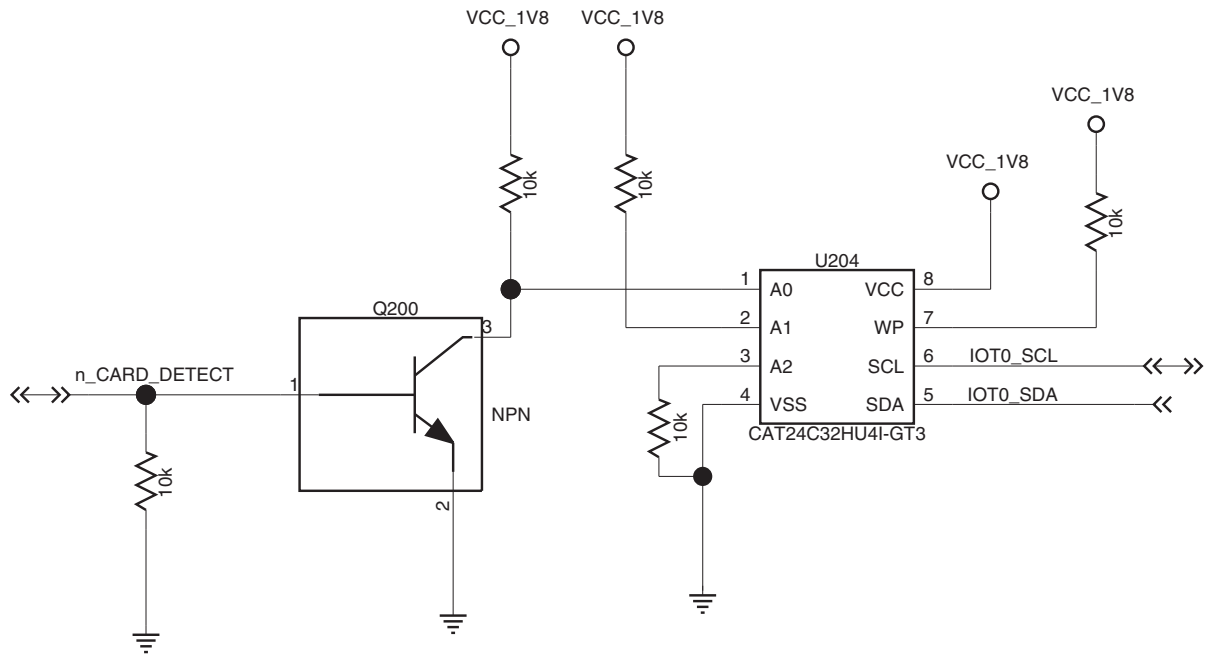


Figure 4-5: Schematic—Recommended EEPROM

Key EEPROM usage notes:

- Active device Address: 0x52
- Inactive Device Address: 0x53
- n\_CARD\_DETECT:
  - Tie to ground using a  $\leq 10k$  pull-down resistor
  - Connect through the transistor to pin A0 on the EEPROM

## 4.4 Module Boot Process

When an IoT Module is detected, the host application reads the module's EEPROM header information (see [EEPROM Header on page 27](#).) This includes the module's slot width (number of slots the module occupies), which the host needs to determine where each module is located. For example, if a 2-slot wide module is in slots 0–1, the host knows the next available slot is slot 2.

[Figure 4-6 on page 30](#) illustrates the module boot process.

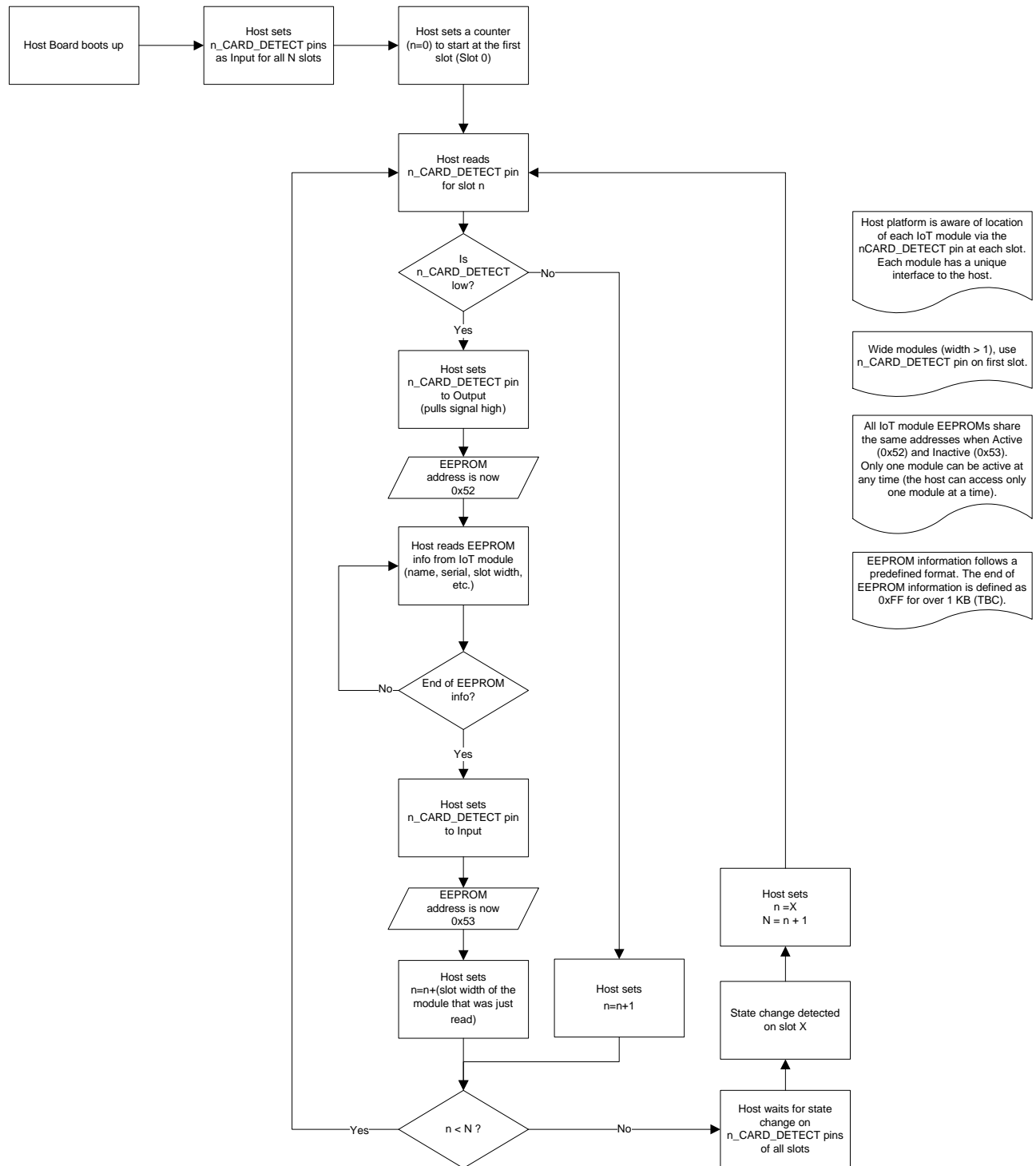


Figure 4-6: Host Process for IoT Module Detection

## 4.5 Host-side Requirements and Considerations

### 4.5.1 IoT Module Connector

IoT Modules connect to host applications via a QSFP+ connector mounted on the host application. This connector style was selected for ease of use, and wide commercial availability from multiple vendors.

The host application can be designed with as many connectors as desired—there is no prescribed limitation on the number of IoT Modules that a host application may support at one time.

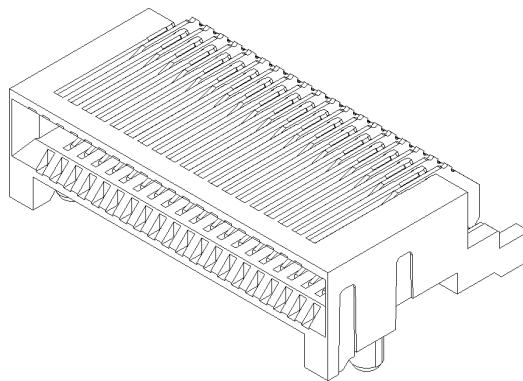


Figure 4-7: QSFP+ Connector

The QSFP+ connector standard is described in SFF-8436 Specification for QSFP+ 10 Gbs 4X Pluggable Transceiver (Standardized as EIA-964 at Rev 4.8 dated October 31, 2013)

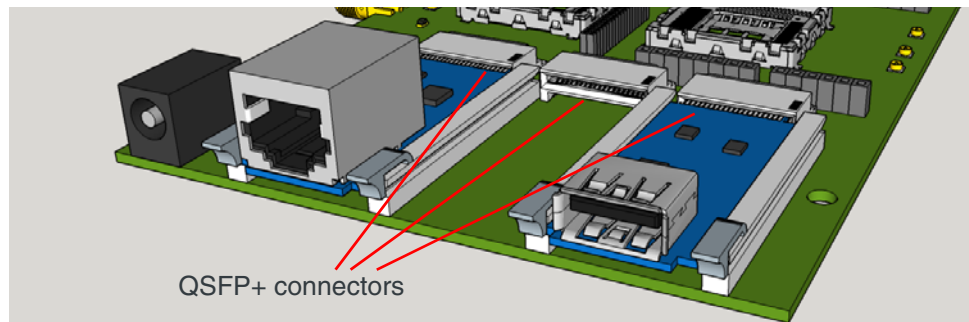


Figure 4-8: Installed QSFP+ Connectors

### 4.5.2 IoT Module Mounts

IoT Modules are mounted on host applications using one of three methods:

- Screwed into spacers
- Screwed into soldered standoffs
- Plugged in via rails

For details, see [Mounting methods on page 33](#).

## 4.6 Pull-up Resistors

All required pull-up resistors (for example, for the I2C interface and n\_CARD\_DETECT) should be located on the host application, not on the IoT Module.

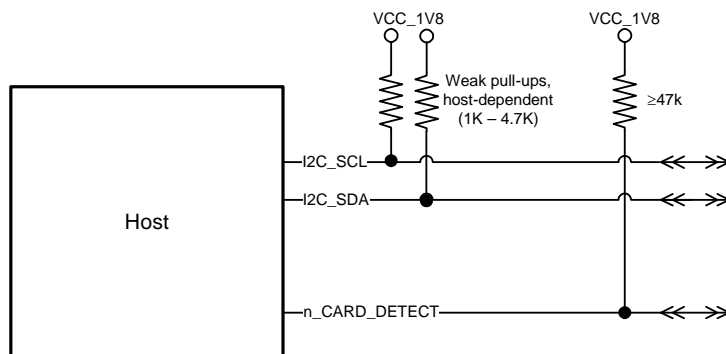


Figure 4-9: Host-side Pull-up Resistor Requirements



# 5: Mounting methods

## 5.1 Overview

This chapter describes methods and hardware specifications for mounting IoT Modules in Host applications.

IoT Module modules are designed to be mounted in host applications via three methods to meet customer requirements:

- Plug in via IoT Module rails. 3D-printing files are available at [source.sierrawireless.com](https://source.sierrawireless.com), and molded versions will be made available in future.
- Screwed into platform via spacers
- Screwed into platform via soldered standoffs

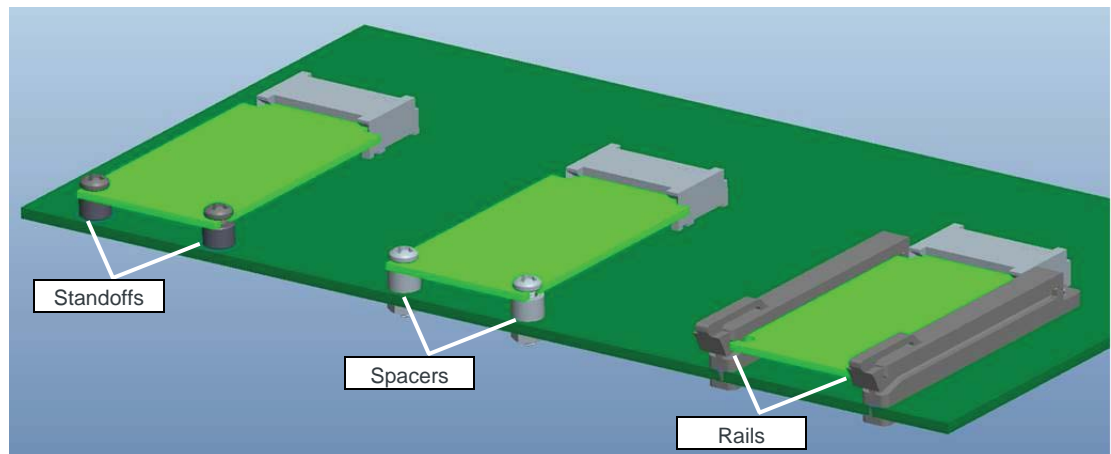


Figure 5-1: Module Mounting Methods

Figure 5-1, [Module Mounting Methods](#), on page 33 and [Figure 5-2, Host-side Mounting Types](#), on page 34 provide detailed specifications for the various mounting types.

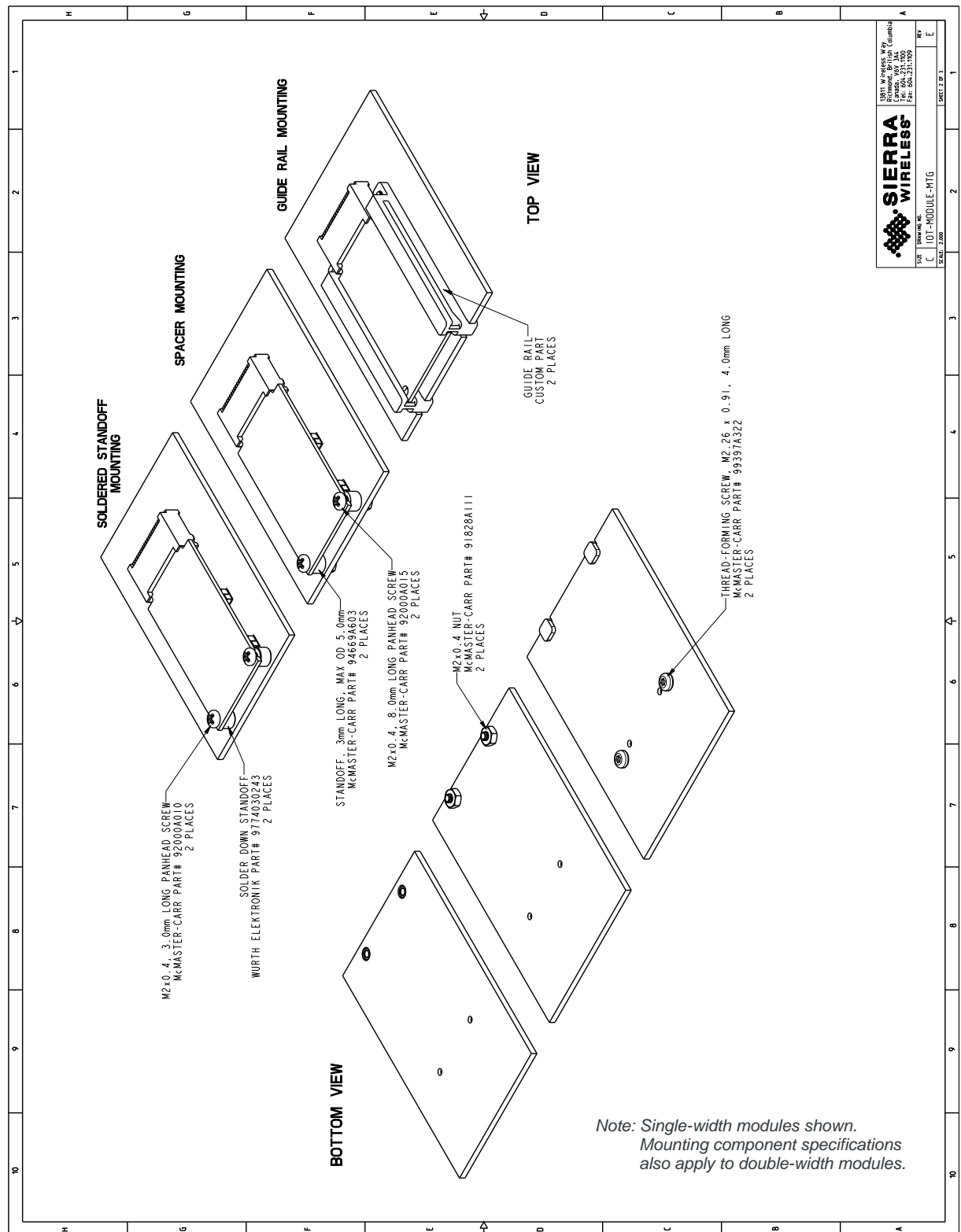


Figure 5-2: Host-side Mounting Types

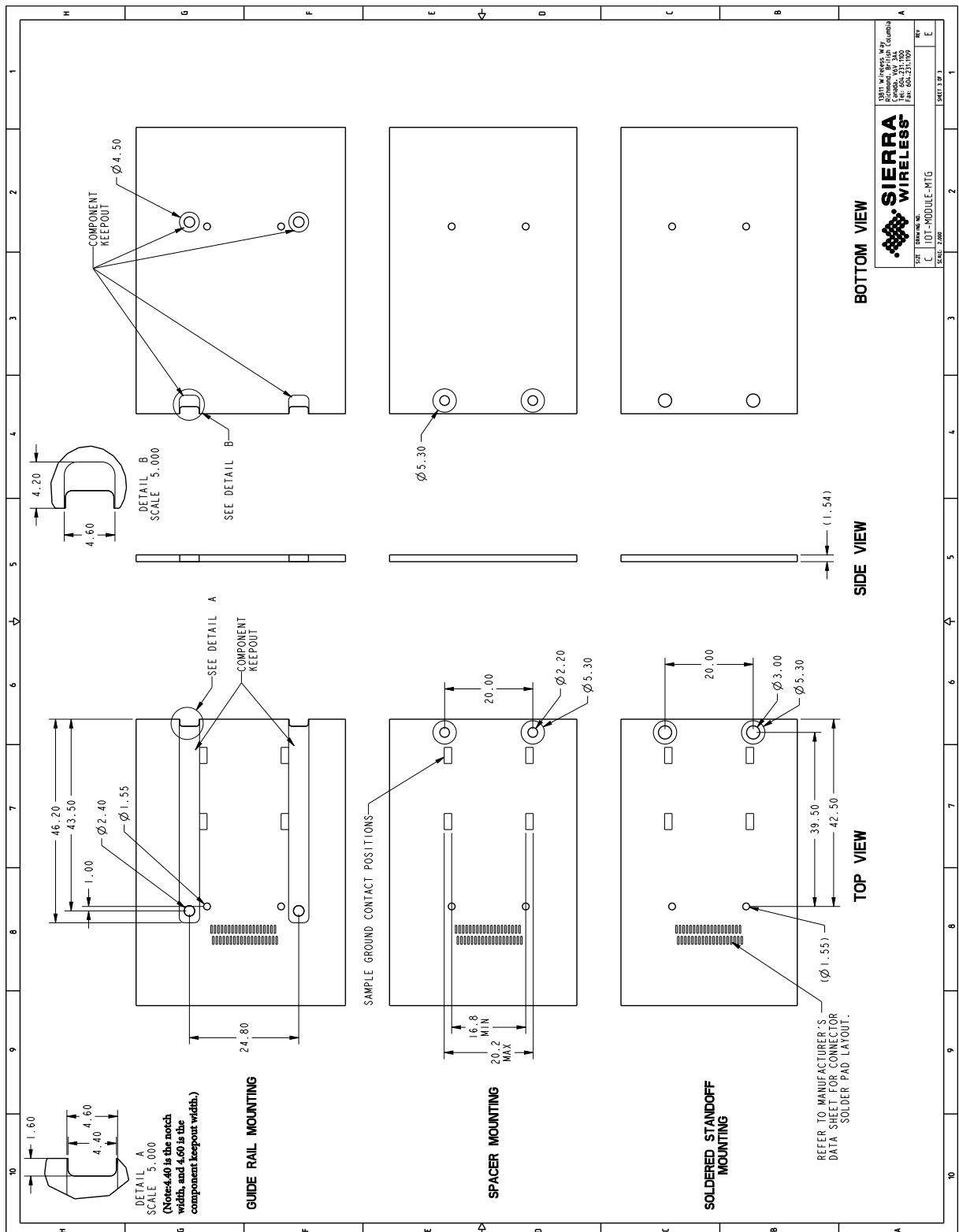


Figure 5-3: Module-side Mounting Details (Single-width Modules)

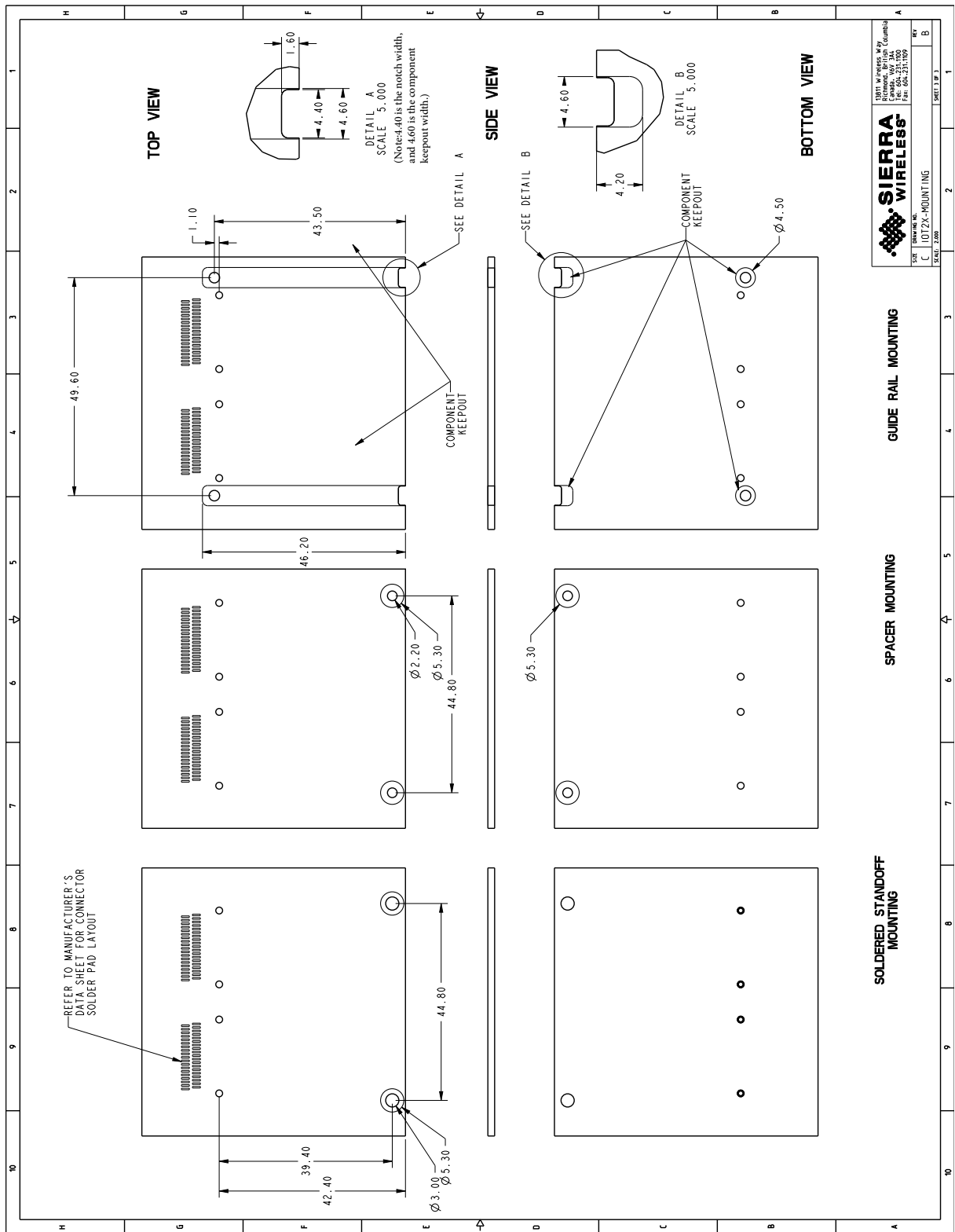


Figure 5-4: Module-side Mounting Details (Double-width Modules)

## 5.2 Self-enclosed IoT Module

When designing an IoT Module, you may want to consider enclosing the PCB in a 'box'. This would make the module less susceptible to incidental damage while storing, handling, and installing.

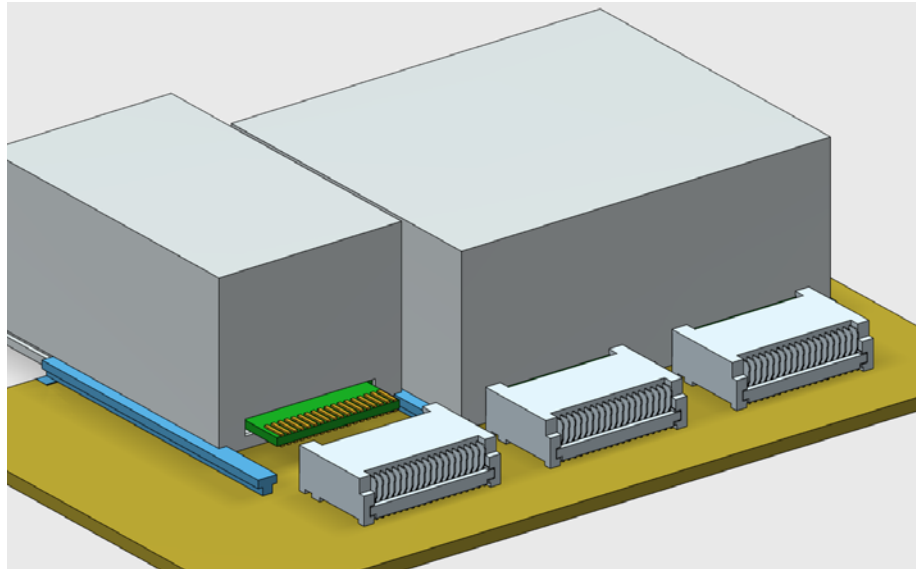


Figure 5-5: Enclosed ('Box') IoT Module Concept—Rear View

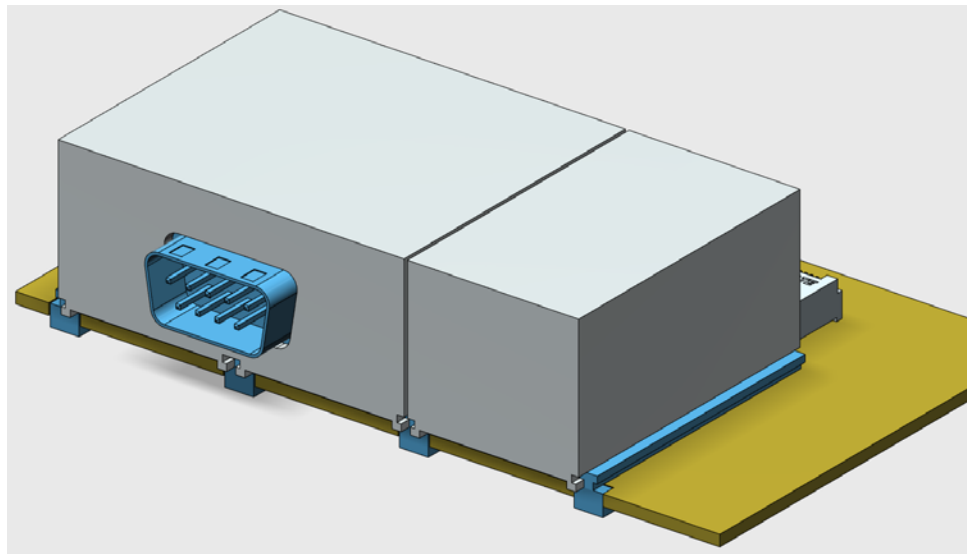


Figure 5-6: Enclosed ("Box") IoT Module Concept—Front View

## 5.3 ESD Protection

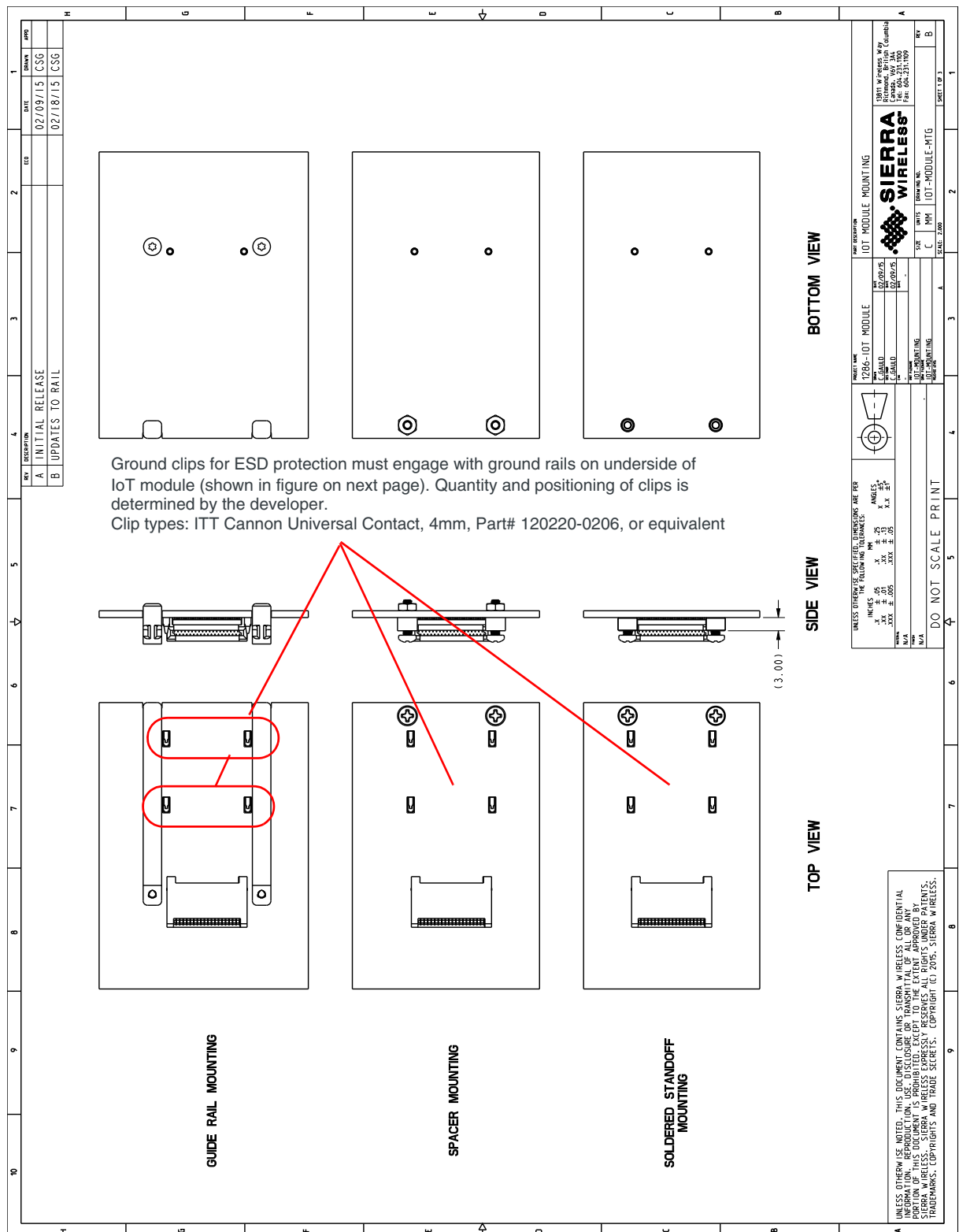
IoT Module mounts on the host application require ground protection appropriate to the mounting method:

- Mounting screws—Either ground the mounting screws, or install grounding clips as described below.
- IoT Module rails—Install grounding clips as described below.

### 5.3.1 Grounding Clips

IoT Modules are designed with copper strips on their bottom side as shown in [Figure 5-8 on page 40](#). A host application can use these strips for grounding by installing grounding clips as shown in [Figure 5-7 on page 39](#). (ITT Cannon Universal Contact, 4mm, part #120220-0206, or equivalent)

When the module is connected to the host, the grounding clips are in contact with the module's copper strips, thus providing protection against ESD zap.



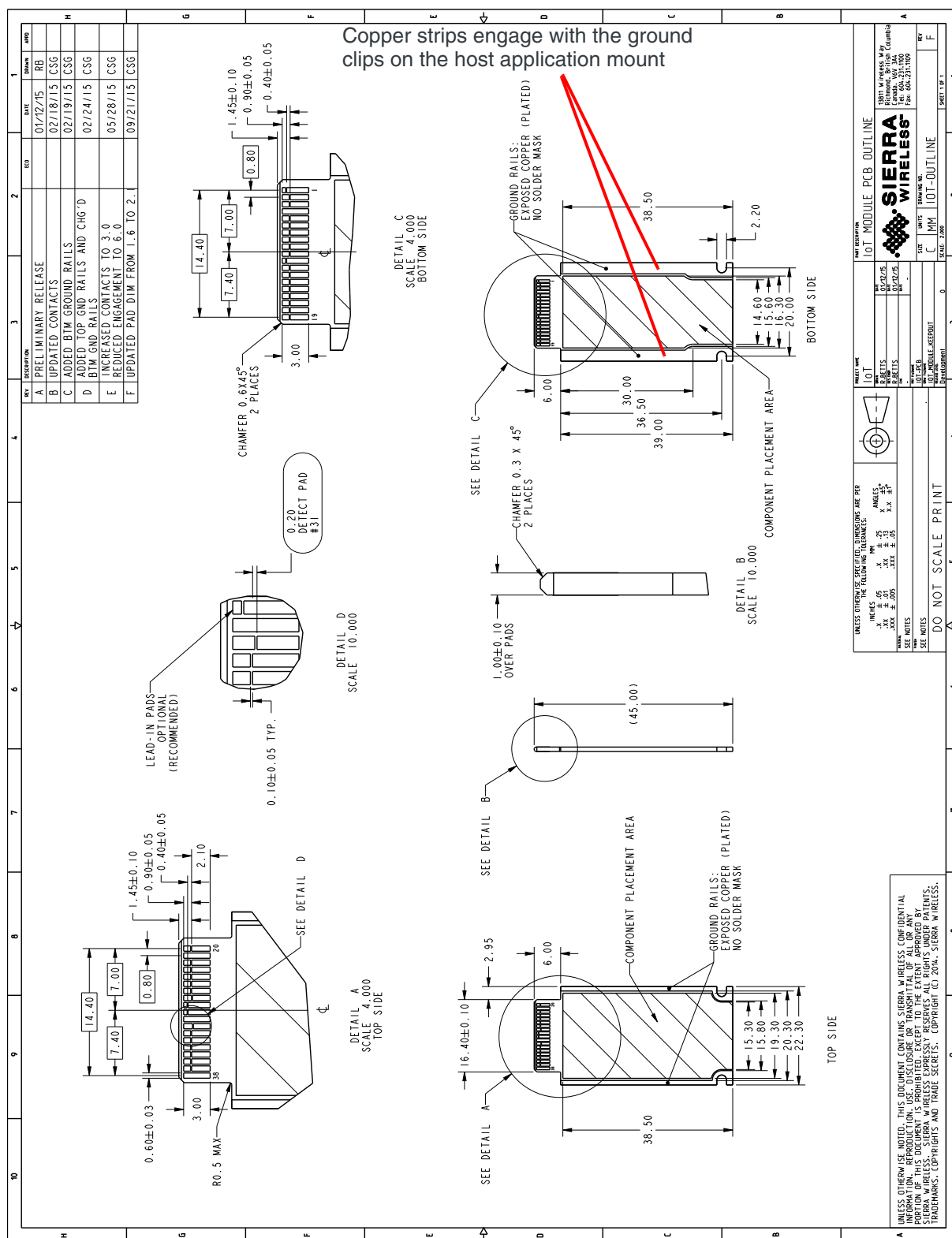


Figure 5-8: IoT Module ESD Protection



# 6: Pinout

## 6.1 Overview

The system interface of the IoT Module is through the gold-plated contacts on the end of the connector (19 on bottom, 19 on top).

## 6.2 Pin Configuration

Figure 6-1 illustrates the IoT Module's connector pin locations.

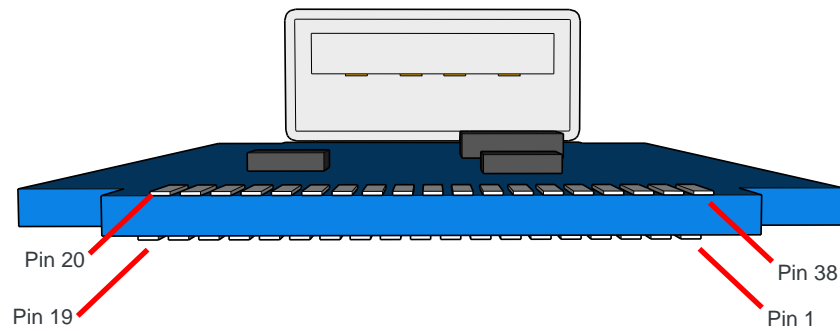


Figure 6-1: IoT Module Connector Pin Locations

Figure 6-2 illustrates the pin configuration.

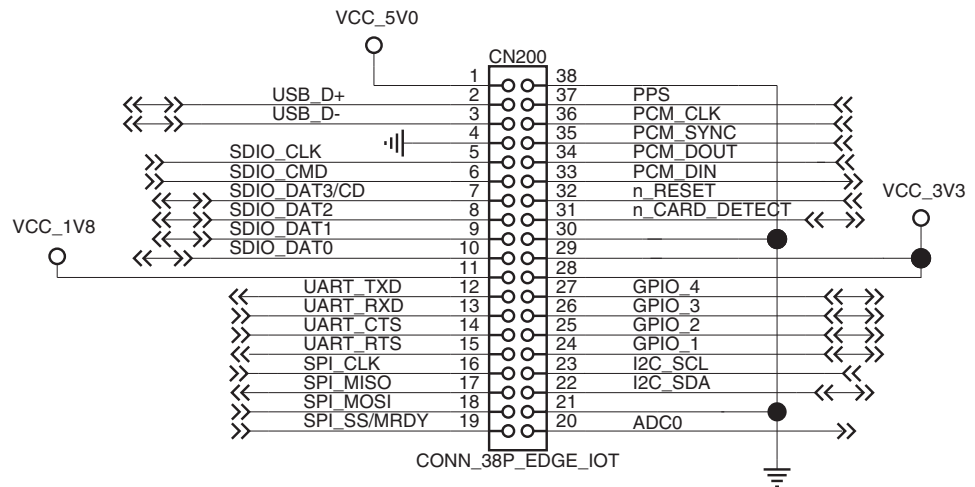


Figure 6-2: Edge Connector (USB/SDIO) Schematic—Module View

## 6.3 Pin Definitions

Table 6-1 lists detailed information for the IoT Module's pin connector.

**Table 6-1: Pin Definitions**

Pin	Group	Signal name	Function	Voltage/Current	I/O <sup>a</sup>
Module bottom side					
1	Power	VCC_5V0	USB power supply/5V power supply	5.0V, 500mA	I
2	USB	USB_D+	USB Data positive	See ([3] Universal Serial Bus Specification, Revision 2.0)	I/O
3	USB	USB_D-	USB Data negative	See ([3] Universal Serial Bus Specification, Revision 2.0)	I/O
4	Power	GND	Ground		-
5	SDIO	SDIO_CLK	SDIO Clock	See footnote <sup>b</sup>	I
6	SDIO	SDIO_CMD	Command/Response	See footnote <sup>b</sup>	I
7	SDIO	SDIO_DAT3/CD	Data 3/Card Detection	See footnote <sup>b</sup>	I/O
8	SDIO	SDIO_DAT2	Data 2	See footnote <sup>b</sup>	I/O
9	SDIO	SDIO_DAT1	Data 1	See footnote <sup>b</sup>	I/O
10	SDIO	SDIO_DAT0	Data 0	See footnote <sup>b</sup>	I/O
11	Voltage reference	VCC_1V8	GPIO voltage output	1.8V $\pm$ 10%	I
12	UART	UART_TXD	UART Transmit data	1.8V $\pm$ 10%	O
13	UART	UART_RXD	UART Receive data	1.8V $\pm$ 10%	I
14	UART	UART_CTS	UART Clear to Send	1.8V $\pm$ 10%	I
15	UART	UART_RTS	UART Ready to Send	1.8V $\pm$ 10%	O
16	SPI	SPI_CLK	SPI clock	1.8V $\pm$ 10%	I
17	SPI	SPI_MISO	SPI master RX data	1.8V $\pm$ 10%	O
18	SPI	SPI_MOSI	SPI master TX data	1.8V $\pm$ 10%	I
19	SPI	SPI_SS/MRDY	SPI Slave Select/Master Ready	1.8V $\pm$ 10%	I
Module top side					
20	Analog	ADC0	Analog to Digital Converter	1.8V max	O
21	Power	GND	Ground		-
22	I2C	I2C_SDA	I2C Tx/Rx data	1.8V $\pm$ 10%	I/O
23	I2C	I2C_SCL	I2C Clock	1.8V $\pm$ 10%	I
24	GPIO	GPIO_1	General purpose I/O	1.8V $\pm$ 10%	I/O

Table 6-1: Pin Definitions (Continued)

Pin	Group	Signal name	Function	Voltage/Current	I/O <sup>a</sup>
25	GPIO	GPIO_2	General purpose I/O	1.8V $\pm$ 10%	I/O
26	GPIO	GPIO_3	General purpose I/O	1.8V $\pm$ 10%	I/O
	SPI	SPI_SRDY	SPI Slave Ready		O
27	GPIO	GPIO_4	General purpose I/O	1.8V $\pm$ 10%	I/O
28	Power	VCC_3V3	3.3V	3.3V $\pm$ 10%, 500mA	I
29	Power	VCC_3V3	3.3V	3.3V $\pm$ 10%, 500mA	I
30	Power	GND	Ground		-
31	DETECT	n_CARD_DETECT	Card detect: Active low detect	1.8V $\pm$ 10%	I/O
32	Reset	n_RESET	Reset module	1.8V $\pm$ 10%	I
33	PCM	PCM_DIN	PCM Data IN (Input to Host)	1.8V $\pm$ 10%	O
	I2S	I2S_IN	I2S Data In (Input to Host)		O
34	PCM	PCM_DOUT	PCM Data OUT (Output from Host)	1.8V $\pm$ 10%	I
	I2S	I2S_OUT	I2S Data Out (Output from Host)		I
35	PCM	PCM_SYNC	PCM Synchronization	1.8V $\pm$ 10%	I
	I2S	I2S_WS	I2S Word Select		I
36	PCM	PCM_CLK	PCM Clock	1.8V $\pm$ 10%	I
	I2S	I2S_CLK	I2S Clock		I
37	Clock	PPS	Stratum Clock 1	1.8V $\pm$ 10%	I
38	Power	GND	Ground		-

a. Direction with respect to IoT Module

b. SDIO card: 2.7–3.6V; Embedded SDIO device: 1.7–1.95V or 2.7–3.6V. See ([4] SD Specifications Part E1 SDIO Simplified Specification, Version 3.00 for details.

# 7: References

For more details, see the references listed below.

## 7.1 Web Site Support

Check the Sierra Wireless Developer Zone at [source.sierrawireless.com](http://source.sierrawireless.com) for the latest documentation available for the IoT Module.

## 7.2 Reference Documents

- [1] High-Speed Inter-Chip USB Electrical Specification, Version 1.0 (a supplement to the USB 2.0 specification)
- [2] Legato.io for Legato API details
- [3] Universal Serial Bus Specification, Revision 2.0
- [4] SD Specifications Part E1 SDIO Simplified Specification, Version 3.00
- [5] RS232 Interface Specification
- [6] I<sup>2</sup>C Specification
- [7] SFF-8436 Specification for QSFP+ 10 Gbs 4X Pluggable Transceiver (EIA-964 Rev 4.8, October 31, 2013)

# A: Abbreviations

**Table A-1: Acronyms and definitions**

Acronym or term	Definition
3GPP	3rd Generation Partnership Project
ADC	Analog to Digital Converter
Bluetooth	Wireless protocol for data exchange over short distances
CLK	Clock
CPU	Central Processing Unit
CTS	Clear To Send
DC	Direct Current
DCD	Data Carrier Detect
EEPROM	Electrically Erasable Programmable Read-Only Memory
EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharges
ETSI	European Telecommunications Standards Institute
GND	Ground
GNSS	Global Navigation Satellite Systems (GPS, GLONASS, BeiDou, and Galileo)
GPIO	General Purpose Input Output
Host	The device into which an IoT Module is inserted
Hz	Hertz = 1 cycle/second
I/O	Input/Output
I2C	Inter-Integrated Circuit
I <sup>2</sup> S	Inter-IC Sound
IoT	Internet of Things
kHz	Kilohertz = 10e3 Hz
LAN	Local Area Network
LPRF	Low-Power RF
LPT	Latchup Protection Technology
M2M	Machine to Machine
MHz	Megahertz = 10e6 Hz
OEM	Original Equipment Manufacturer—a company that manufactures a product and sells it to a reseller.

**Table A-1: Acronyms and definitions (Continued)**

Acronym or term	Definition
PAN	Personal Area Network
PCB	Printed Circuit Board
PCM	Pulse Code Modulation
PPS	Pulse Per Second
RTS	Request To Send
RX	Receive
SDIO	Secure Digital Input/Output
SPI	Serial Peripheral Interface
TBC	To Be Confirmed
TBD	To Be Determined
TX	Transmit
UART	Universal Asynchronous Receiver-Transmitter
USB	Universal Serial Bus
VCC	Supply voltage
WAN	Wide Area Network